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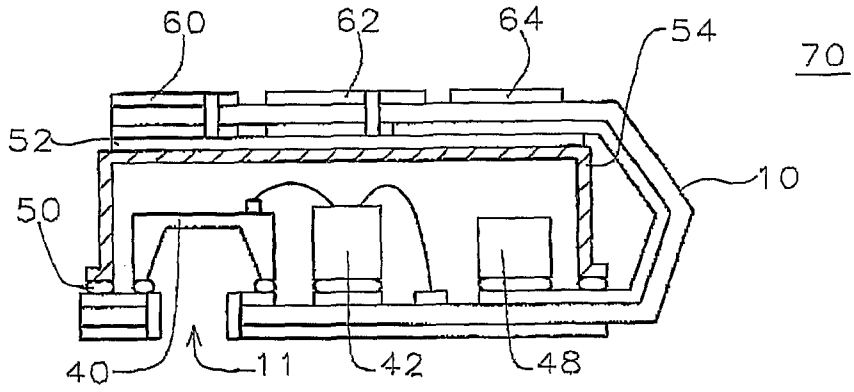
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— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*
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(54) Title: A NEMS PACKAGE USING FLEXIBLE SUBSTRATES, AND METHOD THEREOF



(57) Abstract: A MEMS package and a method for its forming are described. The MEMS package has at least one MEMS device (40) located on a flexible substrate (10). A metal structure (54, 56) surrounds the at least one MEMS device (40) wherein a bottom surface of the metal structure (54, 56) is attached to the flexible substrate (10) and wherein a portion of the flexible substrate (10) is folded over a top surface of the metal structure (54, 56) and attached to the top surface of the metal structure thereby forming the MEMS package.

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